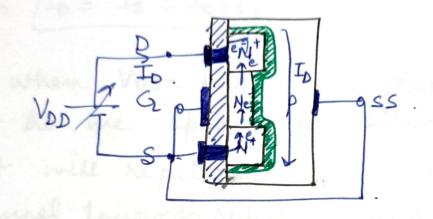


Working of N-channel Depletion-type MOSFET.

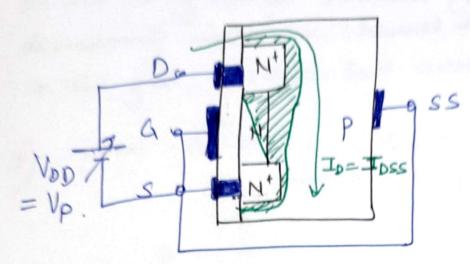


1) when Vos = + ne, Vas = OV.

* As we apply + we voltage to the Drain to Source (electrons will start moving from source to drain) and hence the current flows through the Drain to Source.

As we keep on increasing Vos the current Ip also increases and in addition to that the depletion layer in the channel also increases and a point will come at which channel gets pinched off

at the drain side



This condition is known as pench off condition and the current becomes constant as $|I_0 = I_s = I_{DSS}|$.

2) when Vos= tre, Vas = 100. -re.

* As we apply -re voltage to the gate
it will repel the electrons of the holes
channel towards substrate and altract the
holes of ptype substrate. Due to this
holes and electrons will recombine and
forms the deplotion layer.

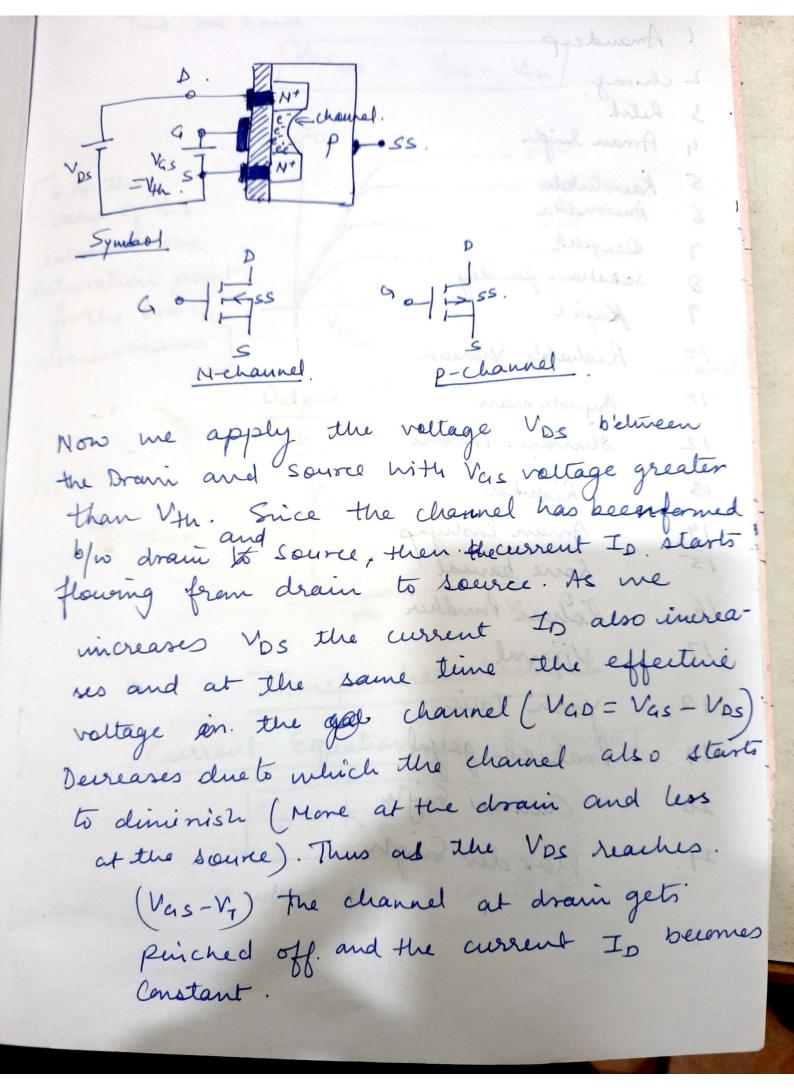
(-ne) leten

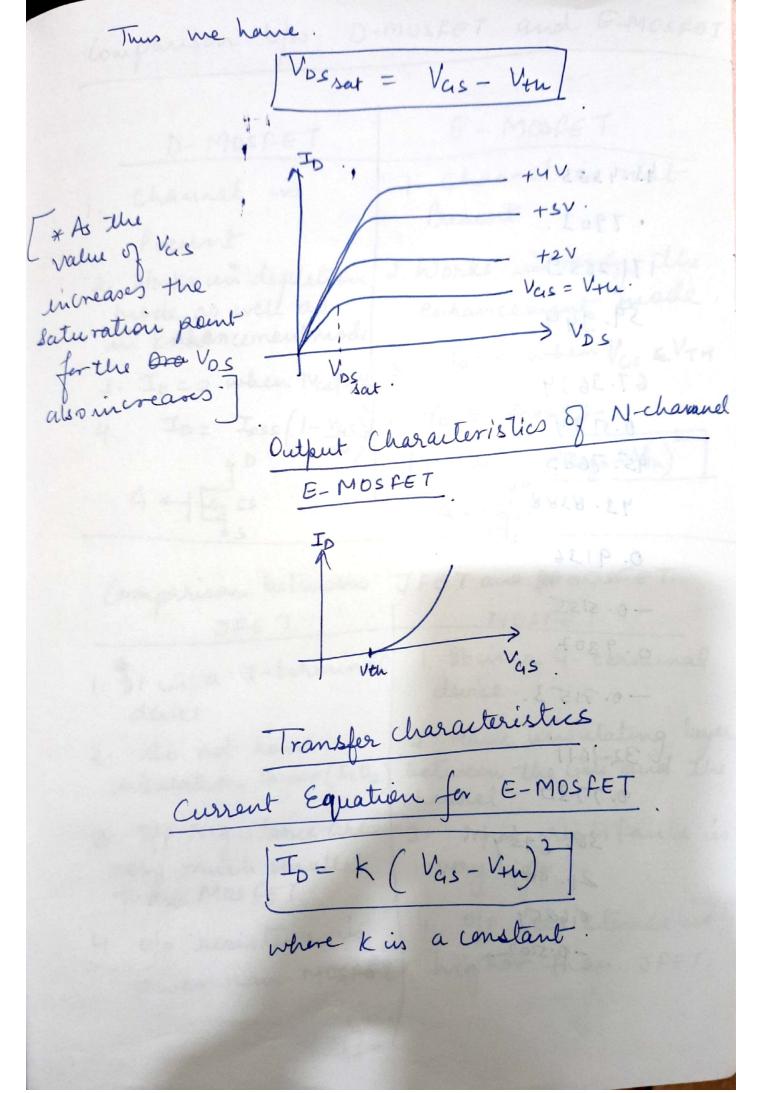
Mence we will say that the Vas (-ve) will help in uncrease of depletien layer and hence the current decreases.

* and In another way, we can say that as the no. of charge curriers (electrons) are decreasing miside the channel due to re voltage on the gate, therefore the current Is decreases. 3) when Vos = +ne, Vas = +ne (bonds break hence no. of electrons increases) They we can say that as the five voltage on the gate increases, the current ID also un breams as the no of charge carriers are incréasing inside - lhe channel. 1 Enhancement Vas = 2V Output Characterists Tromefer characteristics To= IDSS (1- Vas Vp)

Enhancement Type MOSFET. (E-MOSFET). (M- channel) 1) Construction Nt Poss. * (No channel Poes ent during construction un E-MOSPET) a offss 4 offss N-channel p-channel Working of M-channel E-MOSFET. 1) when Vos= +ve, Vas=ov -1 NO current flows, due to depleteon layer between - the P-H junction. 2) when VDS = +ve, Vas = -ve. -> No curren flows, As it support-the formation of depletien layer.

3) when Vas=+ne 800 280 A GENERAL P. SIS & The positive voltage on gate will sepel the holes and attract the electrons of the Ptype S/c. dhe to the SiOz layer the electrons do not reaches the gate and gets accumulated near the surface of SiO2 layer. As we keep on increasing the voltage on Gate, a stage will come at which a thin layer formed at the surface which will have largest no of electrons as compared to holes and hence we will to say that the p-type S/c has been changed unto N-type. This layer is called unversion and Source. as a channel b/w the drain * The Value of Vas at which inversion layer creates as a channel b/w Drain and Source is called Threshold rollage (V+n).





Thus we have. Vossat = Vas - Vtn * As the increases the Saturation point for the ora Vos also increases. Characteristics of N-chammel E-MOSFET Transfer characteristics E-MOSFET Current Equation for ID= K (Vas-V+n)